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Applicant	: Hayashi et al.
App. No	: 10/565,696
Filed	: January 24, 2006
For	: RESIN FOR RESIST, POSITIVE RESIT COMPOSITION AND METHOD OF FORMING RESIST PATTERN
Examiner	: Huhn, Richard A.
Art Unit	: 1796

Mail Stop Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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